L Number	Hits	Search Text	DB	Time stamp
-	. 6 .	5156729.pn. 4108739.pn.	USPAT;	2003/04/16
			US-PGPUB;	09:03
			EPO; JPO;	
			DERWENT	
	23	205/102,104,157,170,176,182.ccls. and ((single or one)	USPAT;	2003/04/16
		adj bath)	US-PGPUB;	09:11
			EPO; JPO;	
	_		DERWENT	
-	. 5	("3770571" "4487654" "4652348" "5052103"	USPAT	2003/04/16
		"5320719").PN.		09:10
-	203	205/102,104,157,170,176,182.ccls. and (laminate or	USPAT;	2003/04/16
		laminated or laminar or multilayered or multilayer or	US-PGPUB;	09:13
		modulated)	EPO; JPO;	03.10
		,	DERWENT	
_	114	205/102,104,157,170,176,182.ccls. and (multilayered	USPAT;	2003/04/16
		or multilayer or modulated)	US-PGPUB;	09:29
		a mamayar or medalaroo,	EPO; JPO;	05.25
			DERWENT	
-	1	205/102,104,157,170,176,182.ccls. and ((compositional	USPAT;	2003/04/16
	-	or structural) adj modulation)	US-PGPUB;	09:39
		or on gordinary day modulariony	EPO; JPO;	05.55
			DERWENT	
_	1543	205/102,104,157,170,176,182.ccls.	USPAT;	2003/04/16
	20.0	2007 102,10 1,107,17 0,17 0,102,0013.	US-PGPUB;	10:49
			EPO; JPO;	10.47
			DERWENT	
_	35	205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor and (printed adj (circuit or wiring) adj	US-PGPUB;	10:56
İ		board))	EPO; JPO;	10.50
			DERWENT	
_	0	419881.apn.	USPAT;	2003/04/16
	o	12,5002.april.	US-PGPUB;	10:51
			EPO; JPO;	10.51
			DERWENT	
_	4	"6309528"	USPAT;	2003/04/16
	*		US-PGPUB;	10:53
			EPO; JPO;	10.55
			DERWENT	
	3	205/\$.ccls. and taylor.in. and inman.in. and sun.in.	USPAT;	2003/04/16
	5	2007 4.5013, and raylor, in. and minuff, in. and surf, in.	US-PGPUB;	10:53
			EPO; JPO;	10.55
			DERWENT	
	15	205/102,104,157,170,176,182.ccls. and		2003/04/14
	15	(semiconductor with (printed adj (circuit or wiring)	USPAT;	2003/04/16
		adj board))	US-PGPUB;	11:04
		aaj boara))	EPO; JPO;	
-	344	205/157 colo	DERWENT	2002/04/44
	344	205/157.ccls.	USPAT;	2003/04/16
			US-PGPUB;	11:25
	İ		EPO; JPO;	
			DERWENT	

•	1341	205/157,170,176,182.ccls.	USPAT;	2003/04/16
			US-PGPUB;	11:27
			EPO; JPO;	
			DERWENT	
	113	205/157,170,176,182.ccls. and (multilayer or	USPAT;	2003/04/16
		multilayered or (multiple adj layer))	US-PGPUB;	11:28
			EPO; JPO;	
			DERWENT	
-	39	(205/157,170,176,182.ccls. and (multilayer or	USPAT;	2003/04/16 11:51
		multilayered or (multiple adj layer))) and tin	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
	. 3	((205/157,170,176,182.ccls. and (multilayer or	USPAT;	2003/04/16
		multilayered or (multiple adj layer))) and tin) and	US-PGPUB;	11:52
		friction	EPO; JPO;	
			DERWENT	
	71	205/157,170,176,182.ccls. and (multichip or "multi chip" or capacitor or resistor)	USPAT;	2003/04/16
			US-PGPUB;	12:58
			EPO; JPO;	
			DERWENT	
	53	205/157,170,176,182.ccls. and ((multichip or "multi chip" or capacitor or resistor) and (printed or semiconductor))	USPAT;	2003/04/16
			US-PGPUB;	12:58
			EPO; JPO;	
			DERWENT	
-	24	205/157,170,176,182.ccls. and ((multichip or "multi	USPAT;	2003/04/16
		chip" or capacitor or resistor) with (printed or	US-PGPUB;	12:58
		semiconductor))	EPO; JPO;	
			DERWENT	1

L Number	Hits	Search Text	DB	Time stamp
37	1412	205/238,239,240,241,242,252,261,263,265,271,281,2	91136BA805.ccls.	2003/04/16
				14:03
38	125	205/238,239,240,241,242,252,261,263,265,271,281,2	911360A805.ccls.	2003/04/16
		and (((wiring or circuit) adj board) or semiconductor)		14:03
39	22	(205/238,239,240,241,242,252,261,263,265,271,281,2	91/3800A3105.ccls	. 2003/04/16
		and (((wiring or circuit) adj board) or semiconductor))		14:04
		and (((multiple or multi) adj layer) or multilayer or		
40	1	((aDffd;288;3)9,240,241,242,252,261,263,265,271,281,	291, 3100 7305.ccl	s.2003/04/16
		and (((wiring or circuit) adj board) or semiconductor))		14:05
		and (((multiple or multi) adj layer) or multilayer or		
41 3 (((aDf)/4)28te, a)99a84(p24tte, 2442p26te, 263, 265, 271, 281, 291, 3100)3				s.2003/04/16
		and (((wiring or circuit) adj board) or semiconductor))		14:05
		and (((multiple or multi) adj layer) or multilayer or		
		multilayered)) and (pulse or pulsed or modulated)		
42	412	205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16 14:11
		(semiconductor or ((wiring or circuit) adj board))	US-PGPUB;	
			EPO; JPO;	
40		100-110	DERWENT	
43	101	(205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16 14:11
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	
		(pulse or pulsed or modulated)	EPO; JPO;	
44	02	//205/102/104/157/170/17//102	DERWENT	
44	82	((205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
		(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
1		(pulse or pulsed or modulated)) and copper	EPO; JPO;	
45	32	(/205/102 104 157 170 174 192 cala and	DERWENT	2002/04/4
73	32	((205/102,104,157,170,176,182.ccls. and (semiconductor or ((wiring or circuit) adj board))) and	USPAT;	2003/04/16
		(pulse or pulsed or modulated)) and tin	US-PGPUB;	14:12
	j	(pulse or pulsed or modulated)) and this	EPO; JPO;	
46	56	((205/102,104,157,170,176,182.ccls. and	DERWENT USPAT;	2003/04/16
	30	(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
		(pulse or pulsed or modulated)) and potential	EPO; JPO;	17-16
		Transport (modulation)) and potential	DERWENT	
47	5	((205/102,104,157,170,176,182.ccls. and	USPAT;	2003/04/16
	-	(semiconductor or ((wiring or circuit) adj board))) and	US-PGPUB;	14:12
		(pulse or pulsed or modulated)) and (reduction adj	EPO; JPO;	
		potential)	DERWENT	